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Invensas and Jabil Collaborate to Qualify BVA Technology for Future Products

SAN JOSE, Calif.--(BUSINESS WIRE)-- Tessera Technologies, Inc. (Nasdaq:TSRA), announced today that its wholly owned subsidiary Invensas Corporation and Jabil (NYSE: JBL), one of the world's leading design and manufacturing product solution providers, have completed the first phase of qualification of Invensas Bond-Via-Array™ (BVA®) interconnect technology.

"BVA is a proven high density, 3D interconnect technology for Package-on-Package (PoP) and System-in-Package (SiP) applications," said Craig Mitchell, president, Invensas. "As an established leader in the manufacture of a diverse array of electronic products, Jabil's identification of BVA as the benchmark for fine pitch package stacking is yet another validation of the value that this technology brings to the industry."

Jabil's interest stems from a desire to address customer requirements to mount fine pitch stacked packages to printed circuit boards (PCBs) with high yield and high throughput. In order to optimize the PCB assembly process of BVA-based packages for high volume production and ensure a complete manufacturing ecosystem, Jabil will also collaborate with Fuji Machine Mfg. Co., Ltd., a leading provider of surface mount technology equipment. The two companies are well suited to make significant contributions in the form of novel and proprietary PCB assembly processes.

"Invensas BVA technology is a low-cost, versatile package stacking solution that is capable of scaling to very fine pitch," said Dan Gamota, vice president of strategic capabilities, Jabil. "At Jabil, we expect such innovative packaging solutions, and our ability to assemble them to PCBs, will be required to address the demand for ever increasing performance and functionality in future customer products. We look forward to continuing to work with Invensas as we explore uses of this important technology."

Invensas BVA technology provides the industry with a scalable package stacking platform that leverages existing manufacturing infrastructure while delivering unmatched tolerance to process variations; this translates into improved yield and cost efficiencies. The technology can be used to provide cost effective 3D interconnect solutions for Package-on-Package (PoP), System-in-Package (SiP) and a range of other packaging applications. For more information on Invensas BVA technology and other Invensas solutions, please visit www.invensas.com or www.tessera.com.

About Tessera Technologies, Inc.

Tessera Technologies, Inc., including its Invensas and FotoNation subsidiaries, licenses technologies and intellectual property to customers for use in areas such as mobile computing and communications, memory and data storage, and 3D-IC technologies, among others. Our technologies include semiconductor packaging and interconnect solutions, and computational imaging and computer vision products and solutions for mobile and other vision systems. For more information call +1.408.321.6000 or visit www.tessera.com or www.invensas.com.

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About Jabil

Jabil is an electronic product solutions company providing comprehensive electronics design, production and product management services to global electronics and technology companies. Offering complete product supply chain management from facilities in 28 countries, Jabil provides comprehensive, individualized-focused solutions to customers in a broad range of industries. Jabil common stock is traded on the New York Stock Exchange under the symbol, "JBL". For further information please visit, www.jabil.com/.

Safe Harbor Statement

This press release contains forward-looking statements, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements involve risks and uncertainties that could cause actual results to differ significantly from those projected, particularly with respect to the characteristics, benefits, and features of BVA and potential future uses of such technology in future products. Material factors that may cause results to differ from the statements made include the plans or operations relating to the businesses of Tessera Technologies,

Inc. (the "Company"); market or industry conditions; changes in patent laws, regulation or enforcement, or other factors that might affect the Company's ability to protect or realize the value of its intellectual property; the expiration of license agreements and the cessation of related royalty income; the failure, inability or refusal of licensees to pay royalties; initiation, delays, setbacks or losses relating to the Company's intellectual property or intellectual property litigations, or invalidation or limitation of key patents; fluctuations in operating results due to the timing of new license agreements and royalties, or due to legal costs; the risk of a decline in demand for semiconductors and products utilizing FotoNation technologies; failure by the industry to use technologies covered by the Company's patents; the expiration of the Company's patents; the Company's ability to successfully complete and integrate acquisitions of businesses; the risk of loss of, or decreases in production orders from, customers of acquired businesses; financial and regulatory risks associated with the international nature of the Company's businesses; failure of the Company's products to achieve technological feasibility or profitability; failure to successfully commercialize the Company's products; changes in demand for the products of the Company's customers; limited opportunities to license technologies due to high concentration in the markets for semiconductors and related products and smartphone imaging; and the impact of competing technologies on the demand for the Company's technologies. You are cautioned not to place undue reliance on the forward-looking statements, which speak only as of the date of this release. The Company's filings with the Securities and Exchange Commission, including its Annual Report on Form 10-K for the year ended Dec. 31, 2015 and its Quarterly Report on Form 10-Q for the quarter ended Mar. 31, 2016, include more information about factors that could affect the Company's financial results. The Company assumes no obligation to update information contained in this press release. Although this release may remain available on the Company's website or elsewhere, its continued availability does not indicate that the Company is reaffirming or confirming any of the information contained herein.

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